

Application Data Sheet
Application Information

Application type:: Regular
Subject matter:: Utility
CD-ROM or CD-R:: None
Number of CD disks:: None
Number of copies of CDs:: None
Sequence submission?::
Computer readable form (CRF)?:: No
Number of copies of CRF::
Title:: THERMAL ENHANCE PACKAGE WITH
UNIVERSAL HEAT SPREADER
Attorney docket number:: YANG31501em
Request for early publication?:: No
Request for non-publication?:: No
Suggested drawing figure:: 3
Total drawing sheets:: 3
Small entity?:: No

Applicant Information

Applicant authority type:: Inventor
Primary citizenship country:: Taiwan, R.O.C.
Status: Full capacity
Given name:: Ching-Hsu
Middle name::
Family name:: YANG
Name suffix::
City of Residence:: Taichung
State or province of residence::

Country of residence:: Taiwan, R.O.C.
Street of mailing address:: No. 3, Lane 63, Shiangshin Rd.,
Nantuen Chiu
City of mailing address:: Taichung
State or province of mailing
address::
Country of mailing address:: Taiwan, R.O.C.
Postal or zip code of mailing
address::

Correspondence Information

Correspondence customer number:: 23364
Phone number:: 703-683-0500
Fax number:: 703-683-1080
E-mail address:: mail@baonthomas.com

Representative Information

Representative customer number:: 23364

Domestic Priority Information

Application:: Continuity Type:: Parent Application:: Parent Filing Date::

Foreign Priority Information

Country::	Application number::	Filing Date::	Priority claimed::
TAIWAN, R.O.C.	091132625	November 5, 2002	YES

Assignee Information

Assignee name::	Advanced Semiconductor Engineering, Inc.
Street of mailing address::	26 Chin 3rd Rd., Nantze Export Processing Zone
City of mailing address::	Kaoshiung
State or province of mailing address::	
Country of mailing address::	Taiwan, R.O.C.
Postal or zip code of mailing address::	